

<b>PCN Number:</b>	20160920004	<b>PCN Date:</b>	Oct. 10, 2016
<b>Title:</b>	Datasheet for DRV8839		
<b>Customer Contact:</b>	<a href="#">PCN Manager</a>	<b>Dept:</b>	Quality Services
<b>Change Type:</b>			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Data Sheet
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Materials
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process

### Notification Details

#### Description of Change:

Texas Instruments Incorporated is announcing an information only notification etc.

The product datasheet(s) is being updated as summarized below.

The following change history provides further details.



**DRV8839**

SLVSBN4C – JANUARY 2013 – REVISED AUGUST 2016

#### Changes from Revision B (December 2015) to Revision C

Page

• Deleted nFAULT from the <i>Simplified Schematic</i> .....	1
• Deleted the NC pins from the <i>Pin Functions</i> table .....	3
• Changed the value of the capacitor on the VM pin from 10 µF to 0.1 µF in the <i>Typical Application Schematic</i> .....	12
• Changed the <i>Layout Guidelines</i> to clarify the guidelines for the VM pin .....	15
• Deleted references to TI's PowerPAD package and updated it with thermal pad where applicable .....	16
• Added the <i>Receiving Notification of Documentation Updates</i> section .....	17

#### Changes from Revision A (January 2014) to Revision B

Page

• Added <i>ESD Ratings</i> table, <i>Feature Description</i> section, <i>Device Functional Modes</i> , <i>Application and Implementation</i> section, <i>Power Supply Recommendations</i> section, <i>Layout</i> section, <i>Device and Documentation Support</i> section, and <i>Mechanical, Packaging, and Orderable Information</i> section .....	1
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The datasheet number will be changing.

Device Family	Change From:	Change To:
DRV8839	SLVSBN4A	SLVSBN4C

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/product/DRV8839>

#### Reason for Change:

To more accurately reflect device characteristics.

#### Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

#### Changes to product identification resulting from this PCN:

None.

#### Product Affected:

DRV8839DSSR			
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For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

<b>Location</b>	<b>E-Mail</b>
USA	<a href="mailto:PCNAmericasContact@list.ti.com">PCNAmericasContact@list.ti.com</a>
Europe	<a href="mailto:PCNEuropeContact@list.ti.com">PCNEuropeContact@list.ti.com</a>
Asia Pacific	<a href="mailto:PCNAsiaContact@list.ti.com">PCNAsiaContact@list.ti.com</a>
Japan	<a href="mailto:PCNJapanContact@list.ti.com">PCNJapanContact@list.ti.com</a>